

Chapter (1)

Physics of MOSFET Transistor

- ⇒ MOSFET structure
- ⇒ MOSFET operation
- ⇒ MOSFET characteristics
- ⇒ MOSFET models
 - ☀ Large signal model
 - ☀ Small signal model

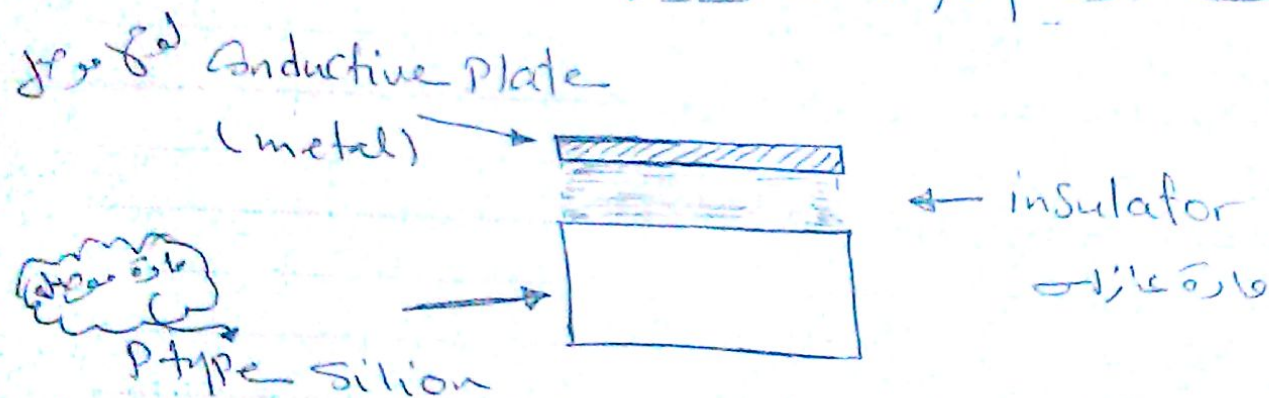
Center Share

لَا إِلَهَ إِلَّا أَنْتَ سُبْحَانَكَ إِنِّي كُنْتُ مِنَ الظَّالِمِينَ

في هذا الباب سوف نتعرف على نوعين من الترانزستور (transistor) وهما MOSFET وهذا النوع له مميزات في الايجتاج عن BJT، سوف نذكر في هذا الباب، سوف يتم (analysis) و (operation) من BJT من حيث التركيب (structure) و العمل (operation) وسوف يتم ايجاد model الخاص به لكي يتم عمل analysis

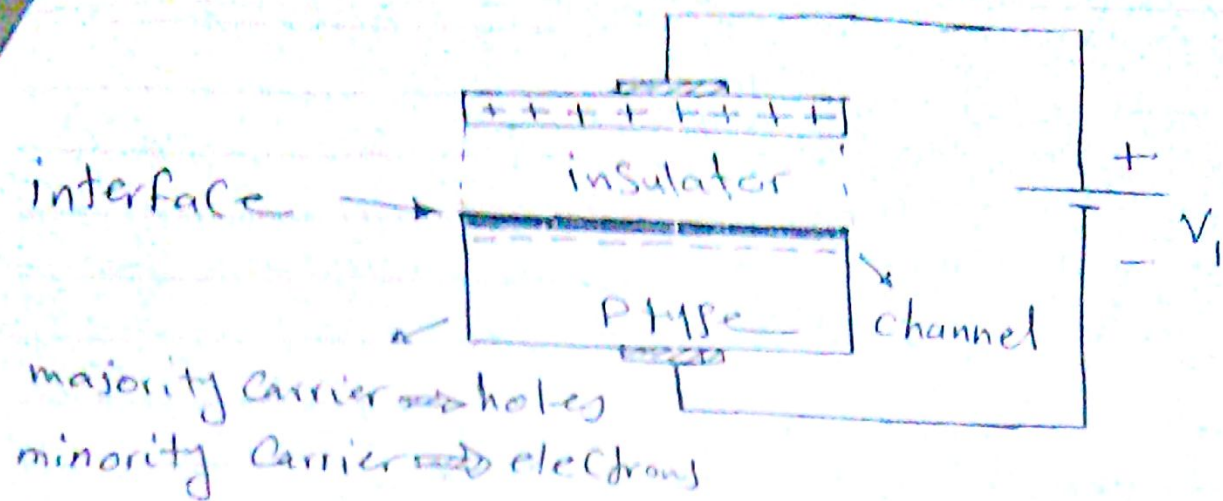
Center Share BJT من حيث التركيب Structure of MOSFET

في ابحاثي لكي نفهم التركيب والاعمال سوف يتم شرح مزايا وعيوب MOSFET



نلاحظ من الشكل السابق انه يعمل كـ (Capacitor)

What happen if a potential difference is applied?
 ماذا يحدث لو قمنا بتطبيق فرق جهد على الالواح او الشكل السابق
 كما في الشكل التالي .



- Positive charge is placed on the top plate.
- الشحنات الموجبة سوف تؤثر على البنية الموجبة.

- Positive charge attracts negative charge

(electrons) from P type.

هذه الشحنات الموجبة سوف تجذب الإلكترونات السالبة الموجودة في

Center Share

P type

- Channel of free electrons may be created at the interface between the insulator and P type

Silicon.

سوف تكون قناة من الإلكترونات الحرة عند السطح الملامس

بين المادة العازلة وفارة السليكون.

وهذه الإلكترونات تكون - سوف تمثل Good Conductive Path

ما هو معدل تركيز electron density الموجودة في

هذه Channel.

the density of electrons in the channel

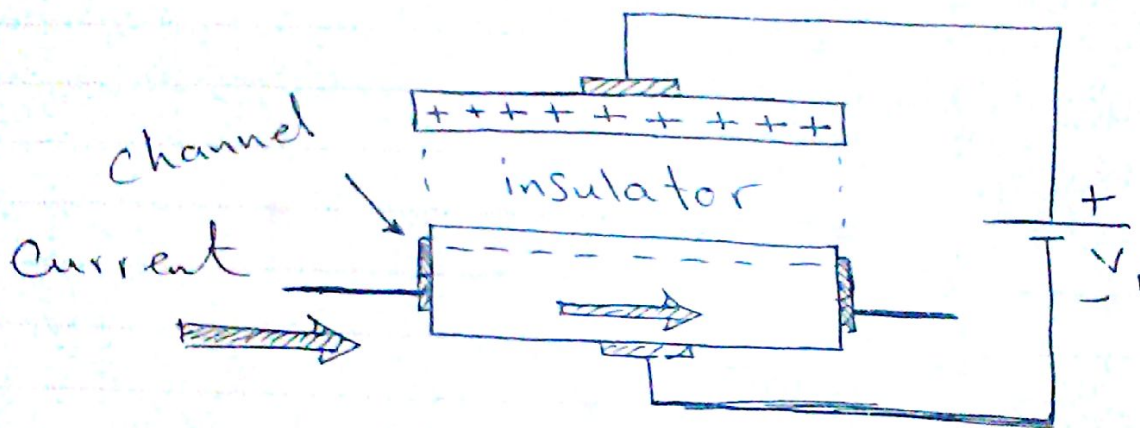
varies with V_1 .

منه يتغير كثافة الإلكترونات في القناة مع V_1

$$\phi = C V$$

ϕ → potential
 C → Capacitance between two plates
 V → the voltage difference between two plates.

منه يتغير كثافة الإلكترونات في القناة مع V



في الشريحة الباقية عن طريق تغيير الجهد بين الحافتين لتتحكم في وجود

Center Share

channel

V_1 Control the current by adjusting the resistivity of channel.

لذلك الجهد V_1 يتحكم في مرور التيار من خلال القناة عن طريق تغيير مقاومتها

channel - لذلك الشريحة الباقية

Voltage Controlled Current Source

V_1 Controls I (Current).

Controlled

$$\Phi = C V$$

$$\frac{1}{t} \downarrow$$

must be maximized

$C \Rightarrow$ maximized (reducing the thickness of dielectric) oxide thickness

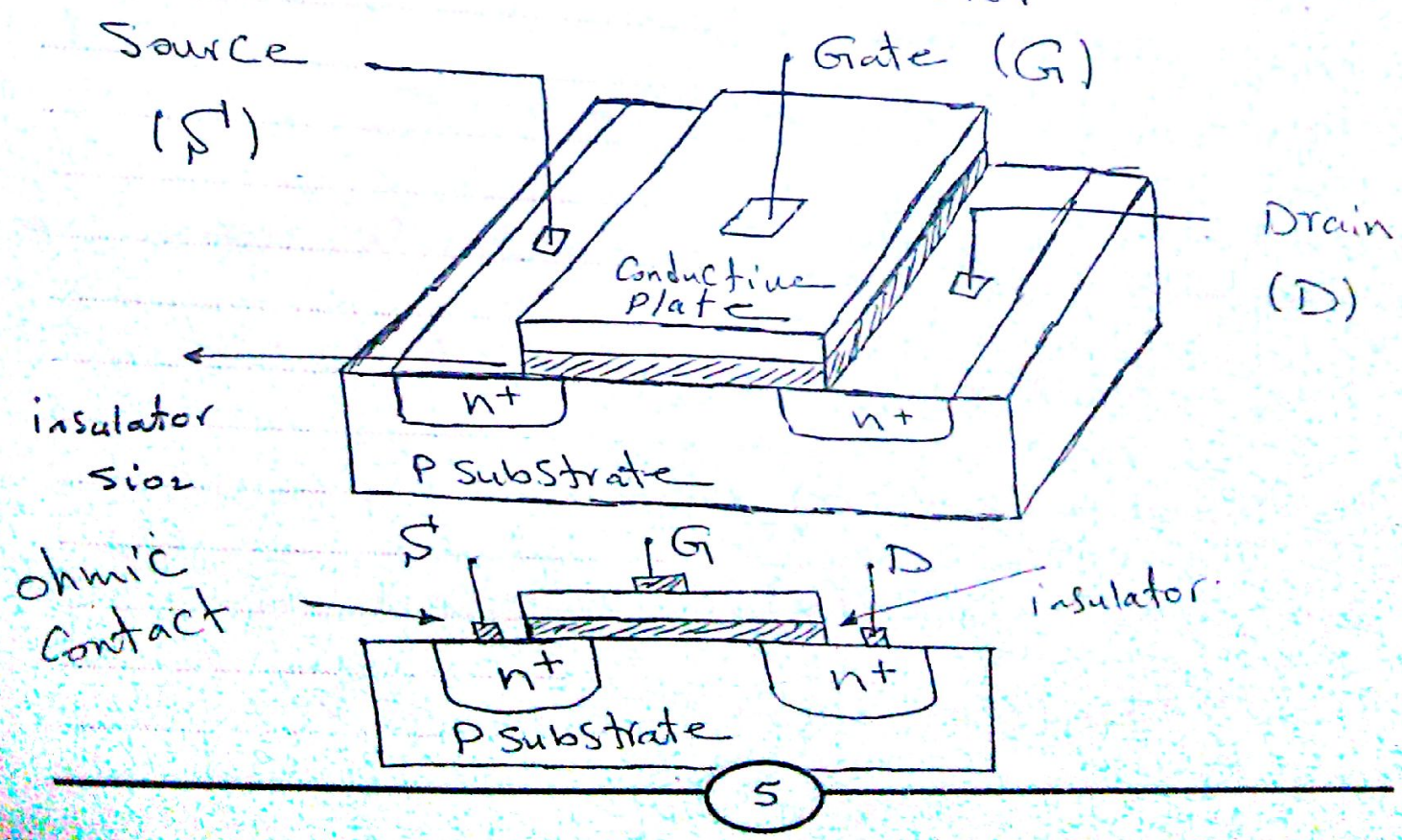
MOSFET Silicon

MOSFET Structure

MOSFET

Center Share

metal oxide semiconductor field effect Transistor



في الشكل، البنية الأساسية

• Gate → Conductive Plate

• Substrate → P-type Silicon

To allow current flow through it.

التي تسمح بمرور التيار، القناة

• Source & Drain

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heavily doped n type regions (n^+)

• doping n type مناطق

Source → Provide charge carriers

• حاملات الشحنة

Drain → absorb charge carriers

Source من حيث الشحنة،

• electrical insulator material → Silicon dioxide

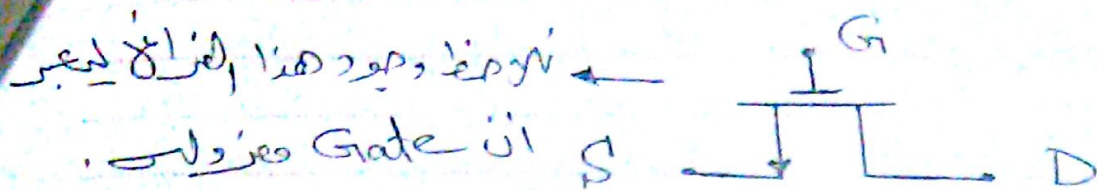
Substrate. & Gate (SiO_2)

القناة التي تتكون من

إلكترونات (electrons)، لذلك يسمى هذا النوع

N MOSFET = nchannel MOSFET

Symbol of NMOSFET



Source مزود في هذا

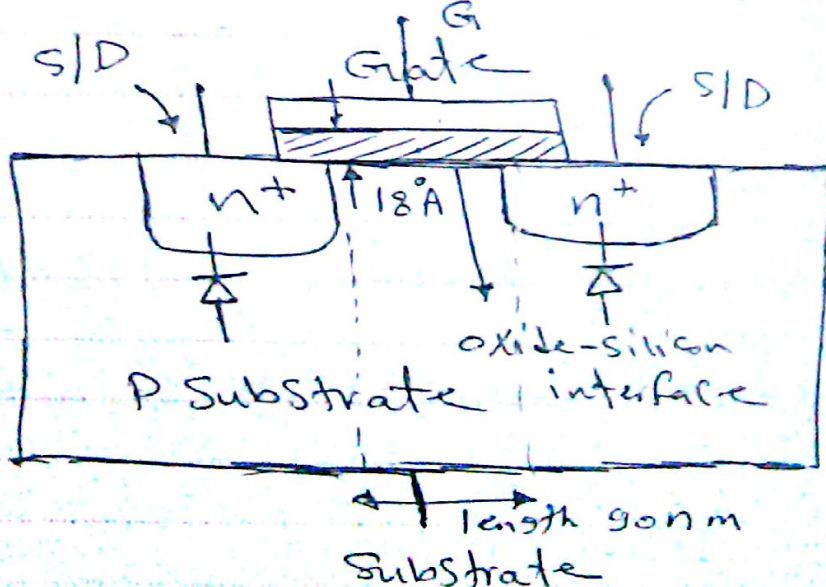
Notes . ملاحظات

- Gate Plate \Rightarrow good Conductor in fact realized by Poly silicon (low resistivity)
- dielectric layer between the gate and Substrate \Rightarrow Silicon dioxide (SiO_2)

Center Share

نرمط هذا الفتح ليغير .
 P type \Rightarrow Drain & Source

PN Junctions (or) Diodes



نوع من الترانزستور، MOSFET

Source & Drain & Gate & Substrate (terminals)

- For Proper operation of transistor must be these Junction reversed biased.

يجب أن يكون MOSFET متحيزاً بشكل صحيح لكي يعمل بشكل صحيح

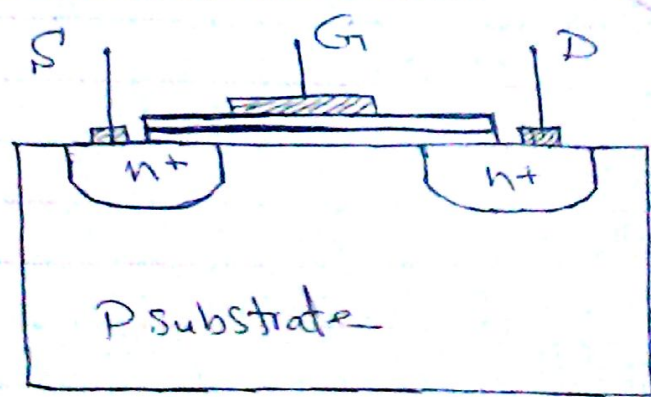
هذه Junctions يجب أن تكون reverse biased.

Source → Substrate. Drain → Substrate

التيار يمر من Source إلى Drain. MOSFET

التيار يمر من Drain إلى Source.

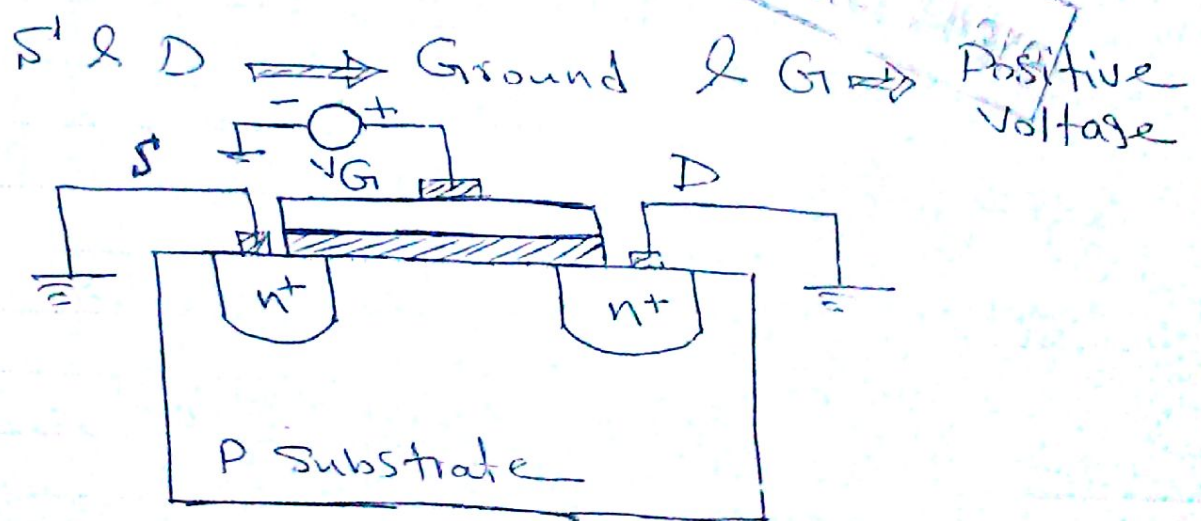
Operation of MOSFET



- MOSFET conduct current between Source and Drain if the channel of electrons is created.
- يتم إنشاء قناة من الإلكترونات بين Source و Drain.

- Channel making when the gate voltage sufficiently positive \rightarrow channel is formed
- channel is formed by the Gate \rightarrow V_G is applied
- V_G is applied \rightarrow Gate current I_G is applied
- SiO_2 is applied \rightarrow substrate is applied \rightarrow Gate
- V_G is applied \rightarrow V_G is applied

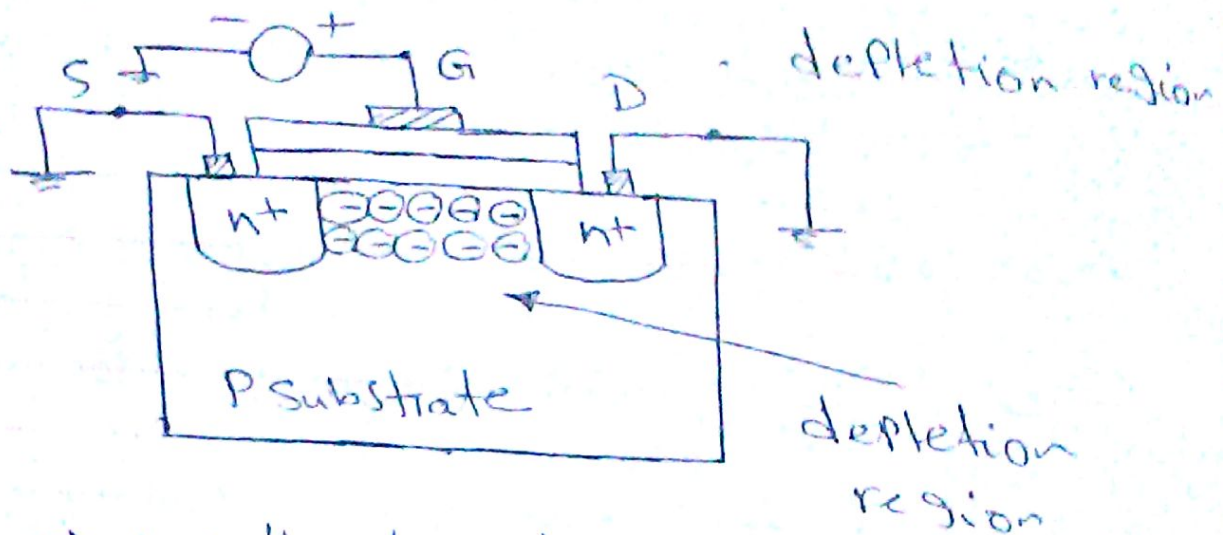
Source and drain are ground and applied a positive voltage to the gate.



- V_G rises \rightarrow Positive charge on the gate \rightarrow V_G is applied
- V_G increased from Zero the Positive charge on the gate repels the holes in the substrate

so that exposing negative ions and creating depletion region.

مع زيادة V_G ، تزداد كثافة الشحنات السالبة على Gate وكون
تزداد holes في substrate وتكون أيونات سالبة مكونة



Note \Rightarrow negative ions immobile charge
شحنات غير متحركة
Center Share
وهذا يخلق ليوم channel لن يكون ليوم مرورا لتيار

No Current can flow from Source to Drain

\therefore MOSFET is off

• Can the Source Substrate and drain Substrate Junctions Carry Current in this mode?

في P-N Junctions لا يمكن أن يمر تيار

To avoid this effect substrate tied to zero
أيضا
 \therefore Diodes not forward Biased

• What happens as V_G increases?

ماذا يحدث مع زيادة V_G ؟

more negative ions are increased so that region under the oxide becoming deeper.

depletion region سوف تزداد الأيونات السالبة وبذلك تزداد المنطقة

• Does this means the transistor never turns on? - off

No. if V_G becomes sufficient positive

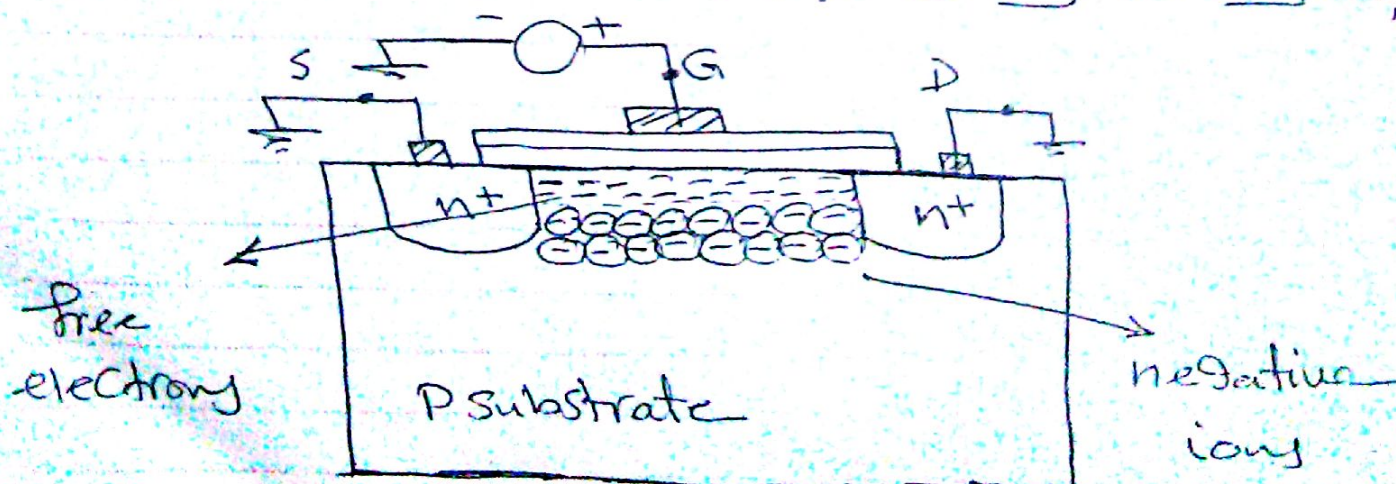
Center Share

عندما تصبح V_G موجبة كافية

free electrons are attracted to the oxide

Silicon interface forming a conductive

channel. القناة سوف تتكون بحدوث



We say the MOSFET on

the gate potential at which the channel begins to appear is called "threshold voltage" (V_{TH})

V_{TH} Channel V_{GS} $V_{GS} > V_{TH}$

V_{TH} range (300mV - 500mV)

- The current that will flow through channel when voltage V_D is applied

Center Share

Drain V_D V_{DS} $V_{DS} > V_{TH}$

Center Share

➡ MOSFET as a variable resistor

channel between S and D as resistor. the value of this resistor changes with Gate Voltage.

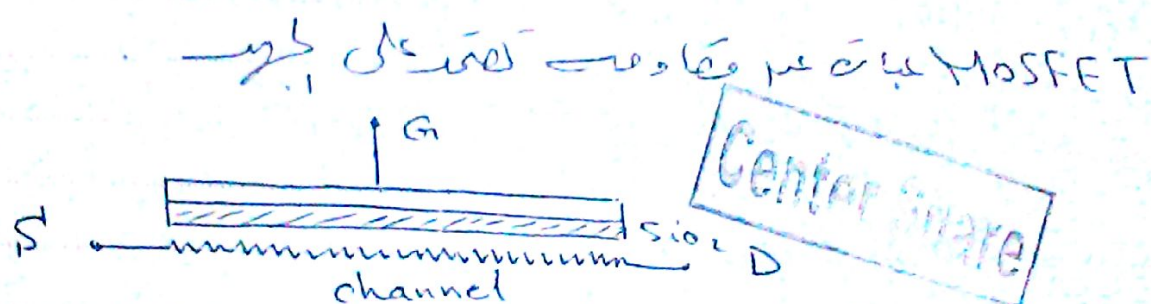
Drain (D) ← channel (Source) (S)

(Gate Voltage) V_G →

$V_G \uparrow \Rightarrow$ density of electron \uparrow

\Rightarrow channel resistor \downarrow

(i.e) MOSFET is Voltage dependent resistor



EX. 1.1

الجزء

in the vicinity of a wireless base station the signal received by a cell phone may become very

قوي

Strong. Possibly "saturating" the circuits and Proh-

يمنع

العمل السليم

المنع

biting Proper operation. Devise a variable gain circuit

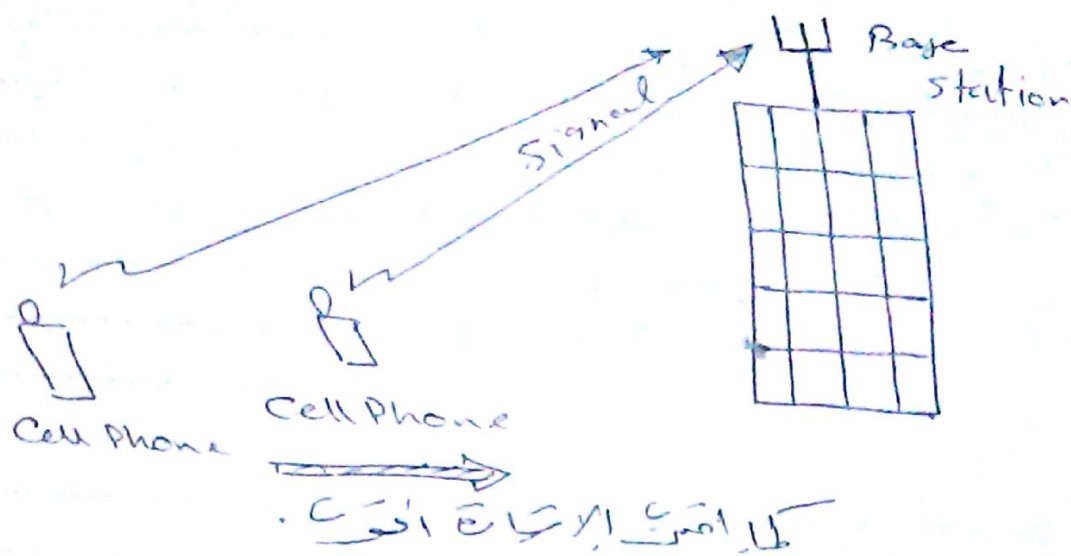
منع

العمل السليم

that lowers the signal level as the cell phone

approaches the Base station.

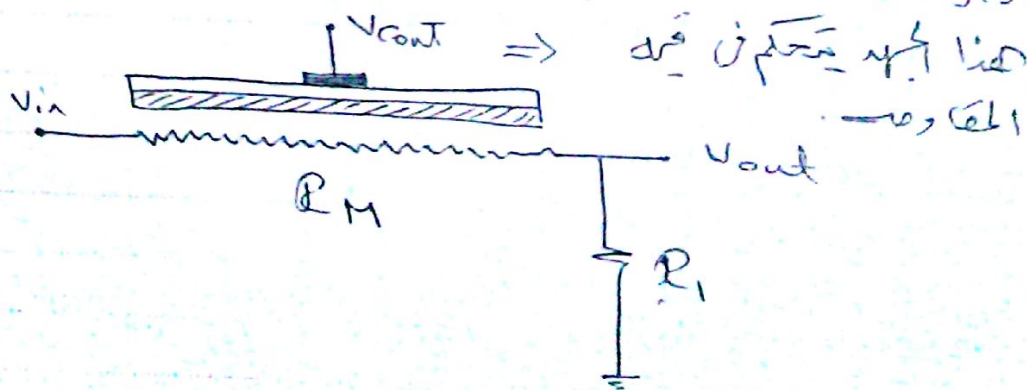
Solution



هذا المثال يوضح بين استخدام MOSFET Variable resistor
 هذا النموذج ككل اقرب من المحطة سوف تكون الإشارة أقوى مما يؤدي
 إلى زيادة أو تلف الدوائر الموجودة داخل المحطة لذلك نحتاج باستخدام
 دائرة تعمل على خفض هذا الإشارة. (نستخدم MOSFET)
 ك مقاومة متغيرة.

Center Share

using MOSFET as Voltage Controlled resistor



$$V_{out} = V_{in} * \frac{R_1}{R_M + R_1}$$

$V_{cont} \downarrow \Rightarrow$ density of electron in channel \downarrow

$R_M \uparrow \Rightarrow V_{out} \downarrow$

(attenuator) \leftarrow $\frac{V_{out}}{V_{in}} = \frac{R_1}{R_M + R_1}$

Note:-

may be using MOSFET as voltage dependent

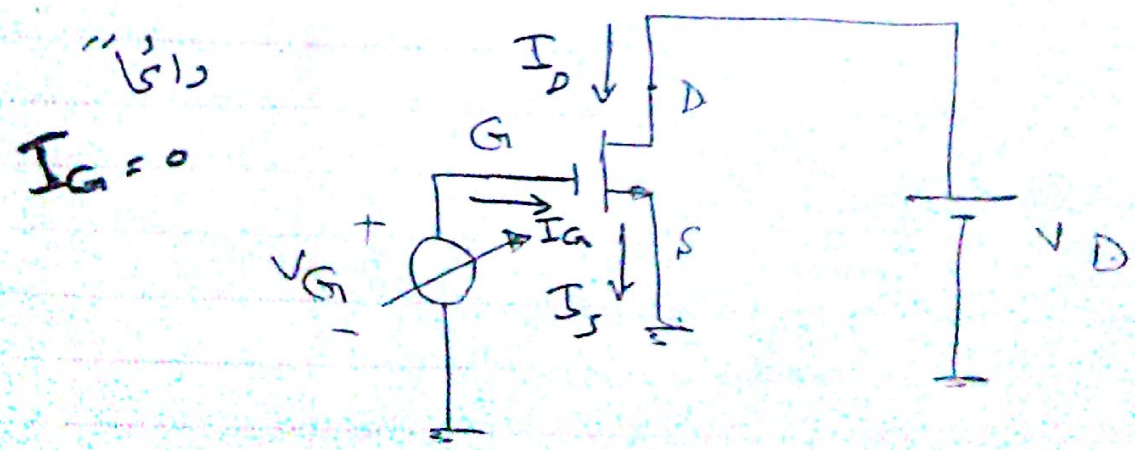
resistor in "Variable gain Amplifier"

Amplifier \Rightarrow MOSFET \Rightarrow $\frac{V_{out}}{V_{in}} = \frac{R_1}{R_M + R_1}$

Center Share \Rightarrow (gain) \Rightarrow $\frac{V_{out}}{V_{in}} = \frac{R_1}{R_M + R_1}$

\Rightarrow MOSFET characteristic Curve

* $I_D - V_G$ characteristic Curve

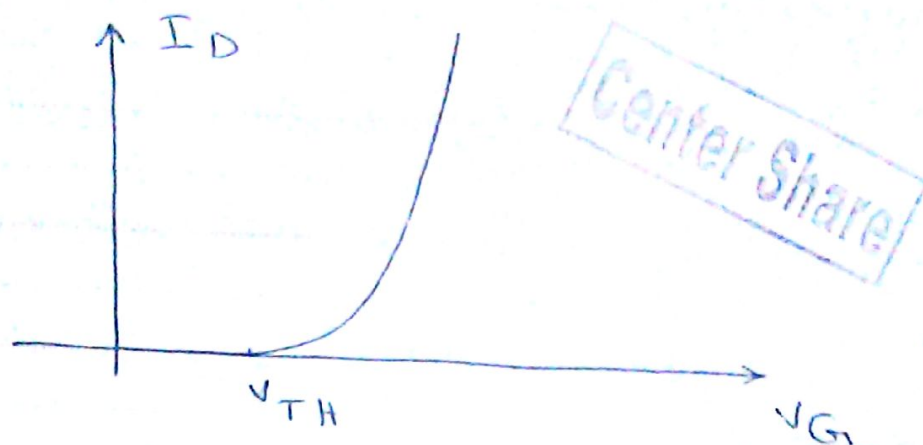


* if $V_G < V_{TH} \Rightarrow$ no channel exists (channel)

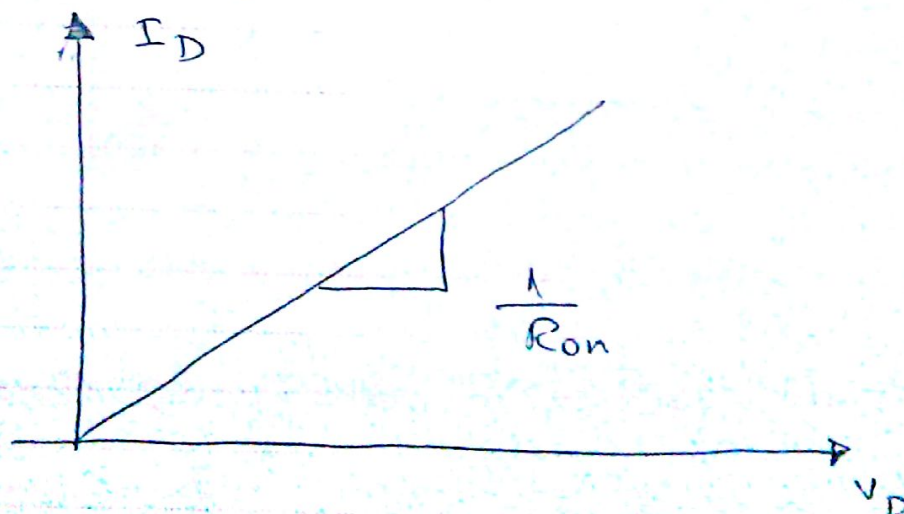
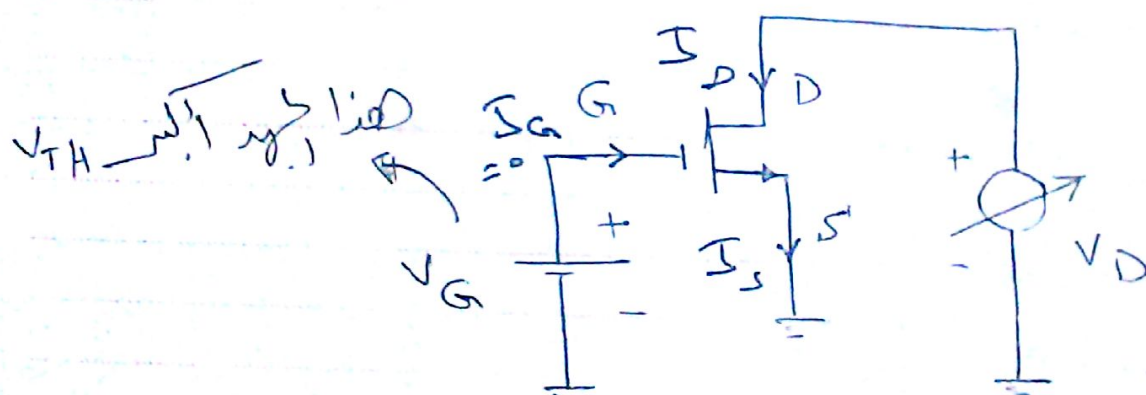
∴ MOSFET off

∴ $I_D = 0 \rightarrow (V_D)$ are not in

* if $V_G > V_{TH}$ ∴ $I_D > 0$



* $I_D - V_D$ characteristic curve



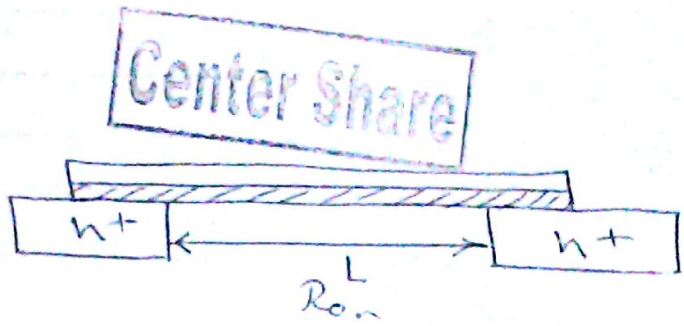
ہم ان کو چاہیے کہ وہ (S) و (D) کے درمیان (drift) ہو جائے اور (channel) کے ذریعے (S) سے (D) تک (drift) ہو جائے۔

EX. 1.2

Sketch I_D vs V_G and I_D vs V_D characteristics for (a) different channel lengths. (b) different oxide thickness.

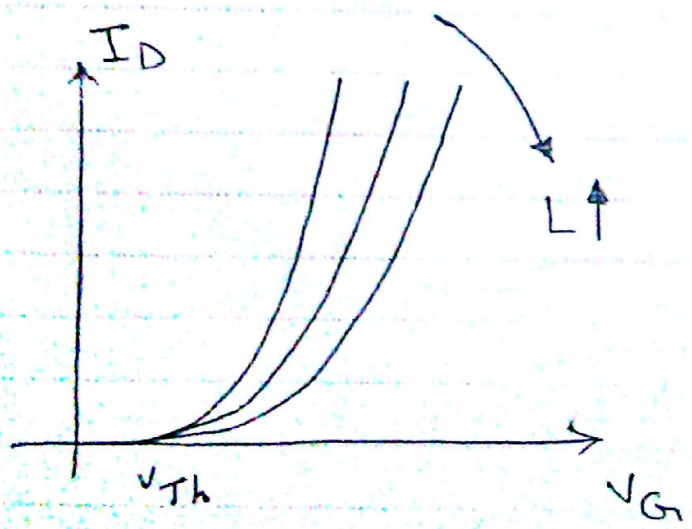
Solution

(a)

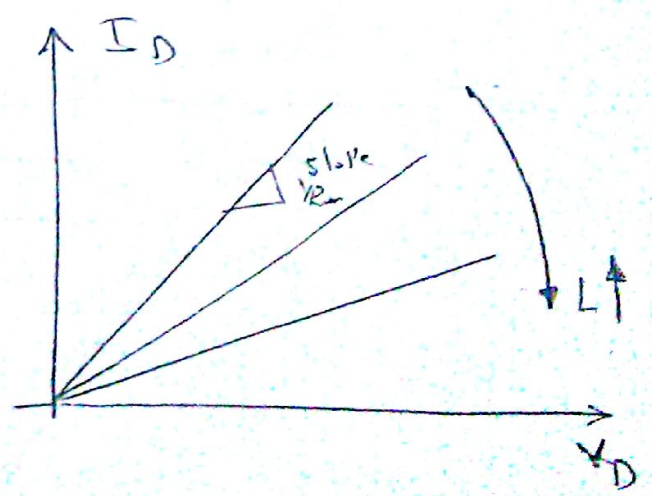


$$R_{on} = \frac{\rho L}{A} \rightarrow \text{channel length}$$

$\therefore L \uparrow \rightarrow R_{on} \uparrow \rightarrow \text{slope} = \frac{1}{R_{on}} \downarrow$



I_D - V_G c/c



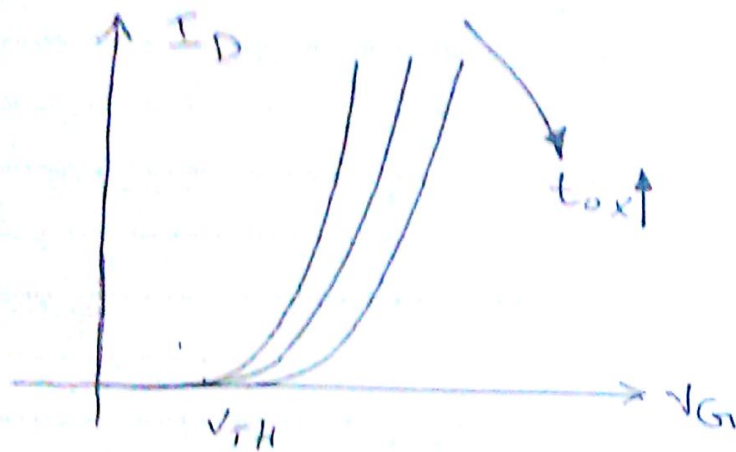
I_D - V_D c/c

(b) different oxide thickness

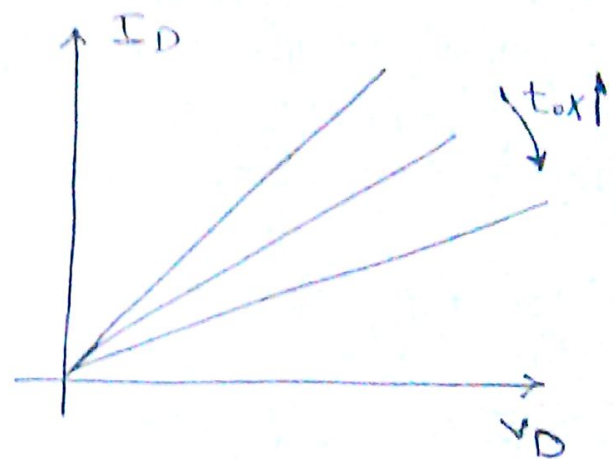


$t_{ox} \uparrow \Rightarrow C \downarrow$ (Capacitance between the Gate and Silicon substrate)

$\therefore \Phi = C'V \downarrow \Rightarrow R_{on} \uparrow \Rightarrow \text{slope} \downarrow$



$I_D - V_G$ c/c

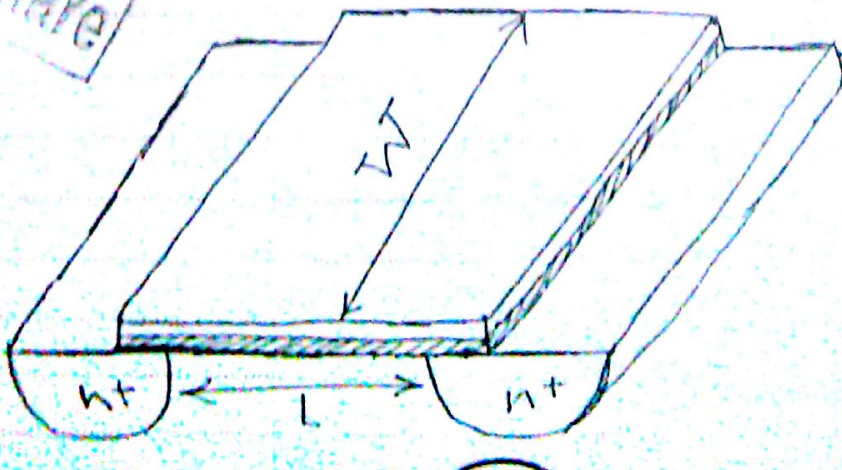


$I_D - V_D$ c/c

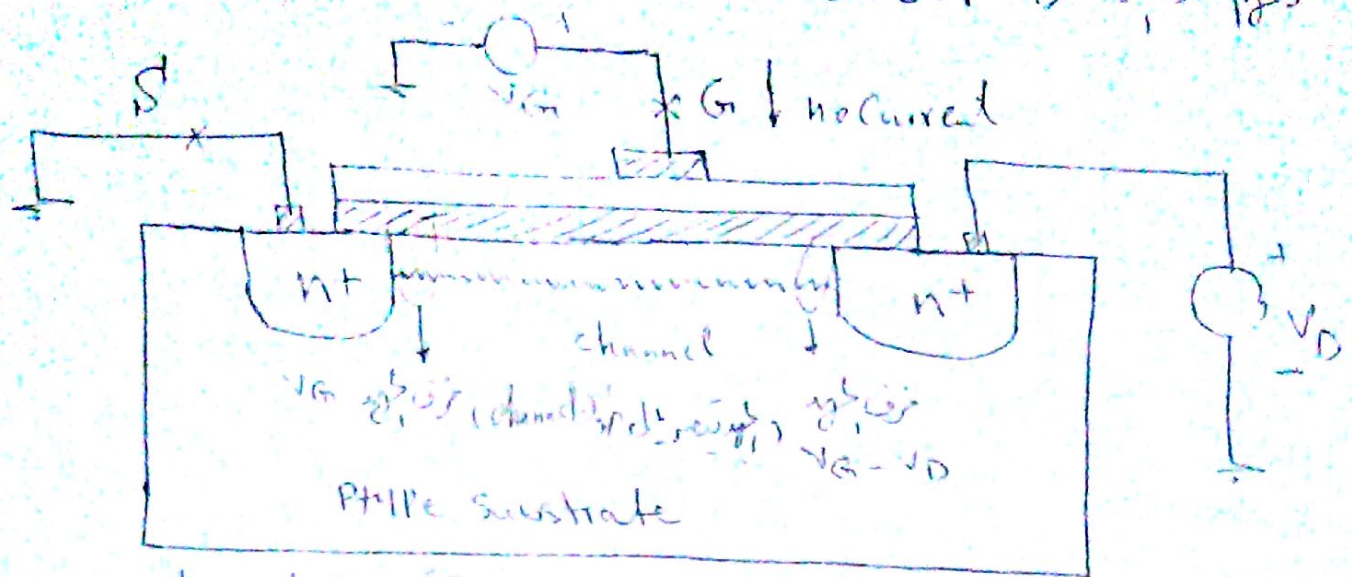
W \Rightarrow (c/c) \Rightarrow width of Transistor or Gate width.

Center Share

W \Rightarrow width of Transistor or Gate width.



To understand this effect. نکته:



channel is formed $V_G > V_{TH}$ و این در نتیجه

When $V_G > V_{TH}$ the MOSFET acts as voltage dependent

resistor. $\text{در این حالت MOSFET به یک}$

resistor acts, $\text{و این در نتیجه channel depth is not uniform}$

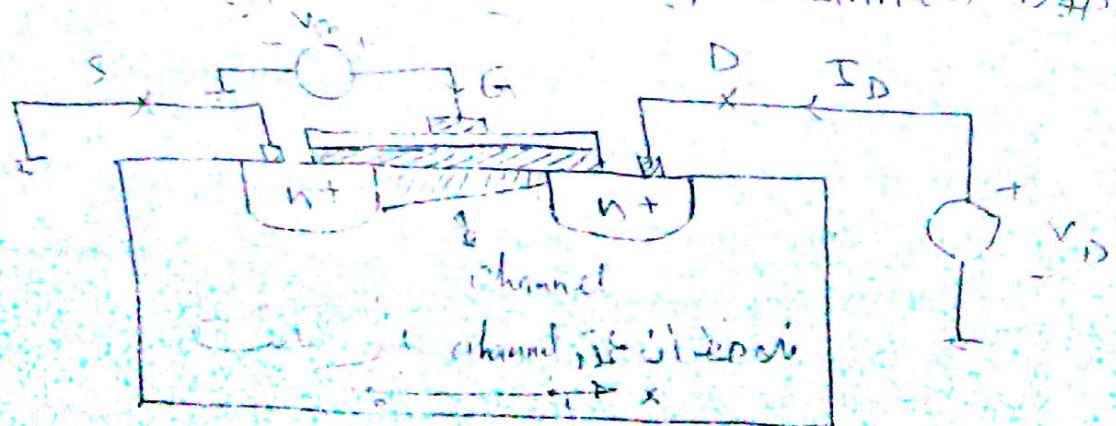
Center Share

و این در نتیجه

(Constant) V_G (Gate voltage) (Gate) و این در نتیجه

nonuniform) و این در نتیجه channel depth is not uniform

substrate, Gate و این در نتیجه (channel) و این در نتیجه



$(V_G - V(x)) > V_{TH}$ → channel is Si channel
 When V_D (increased) ↑

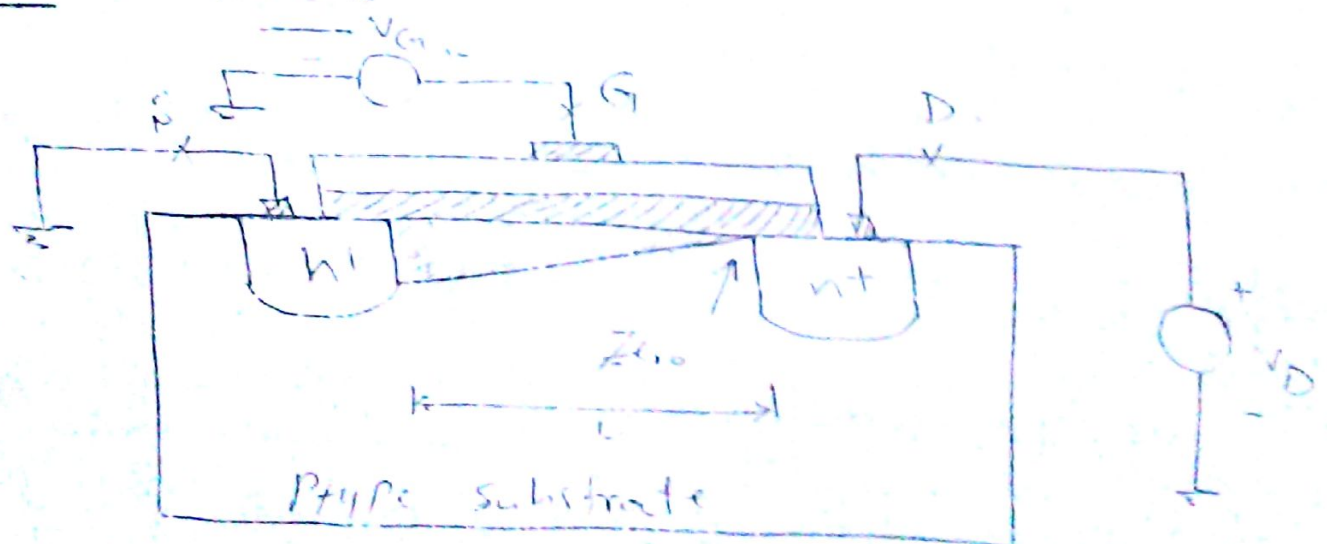
∴ the channel depth decreases at drain
 When $V_G - V_D = V_{TH}$

∴ the channel depth at the drain end decreases to almost zero

Center Share

∴ Drain & channel is V_D → V_D is $V_G - V_D = V_{TH}$ → $V_D = V_G - V_{TH}$

∴ the channel is said to be Pinched off



Pinch off at

$$V_G - V_D = V_{TH}$$

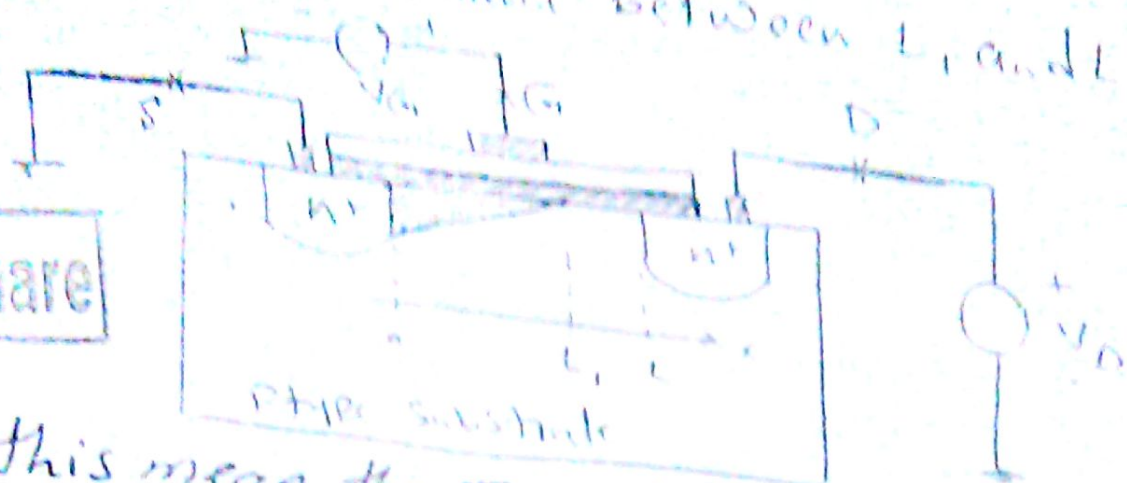
or

$$V_D = V_G - V_{TH}$$

or When $V_{GS} > V_{GS} - V_{TH}$

→ MOSFET No channel between L and D

Center Share



Does this mean the Transistor cannot conduct Current?

→ No, MOSFET is still conducting

→ No. MOSFET conducts.
 → No channel
 → (electric field) E_{ox} is high
 → (electric field) E_{ox} is high

→ Pinch off
 → (MOSFET) I_D is constant
 → Constant Current Source I_D is constant
 → I_D is constant

⇒ Derivation of I-V characteristics

* channel charge density.



require an expression for channel charge
(free electrons) per unit length \equiv channel density
(for e.g. for channel Q_{ch} per unit length Q_{ch}/L) \rightarrow channel density n

$$\text{channel density} = \frac{\text{channel charge}}{\text{unit length}}$$

$$\therefore Q = C V$$

Center Share

$C \equiv$ Gate Capacitance per unit length

$V \equiv$ Voltage difference between Gate and channel

$\therefore Q \Rightarrow$ charge density. (Q/L)

$C_{ox} \equiv$ gate Capacitance per unit area (F/m^2)
channel & Gate C_{ox} C_{ch} C_{gs} C_{gd} C_{ds}

$$\therefore C = W C_{ox}$$

Capacitor per unit length

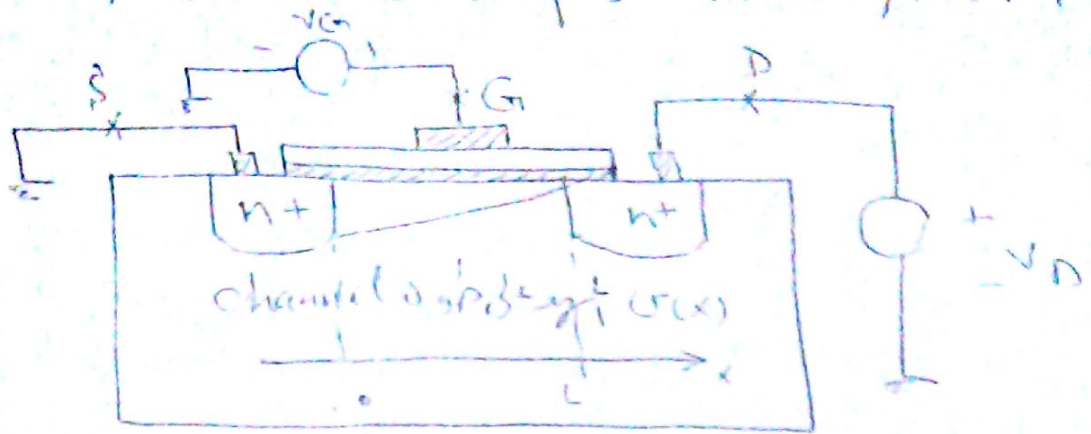
width of MOSFET

(Ground) \rightarrow $V_G = V_{GS}$ $V_D = V_{DS}$

$$\therefore V_G = V_{GS} \quad V_D = V_{DS}$$

$V_{GS} \neq V_{DS}$ \rightarrow $V_{GS} \neq V_{DS}$

Q charge density = Coulomb/meter



$(V_{GS} - V(x) - V_{TH}) \Rightarrow$ channel charge density in C/m^2

$$\therefore Q(x) = W C_{ox} [V_{GS} - V(x) - V_{TH}]$$

$$0 < V(x) < V_D$$

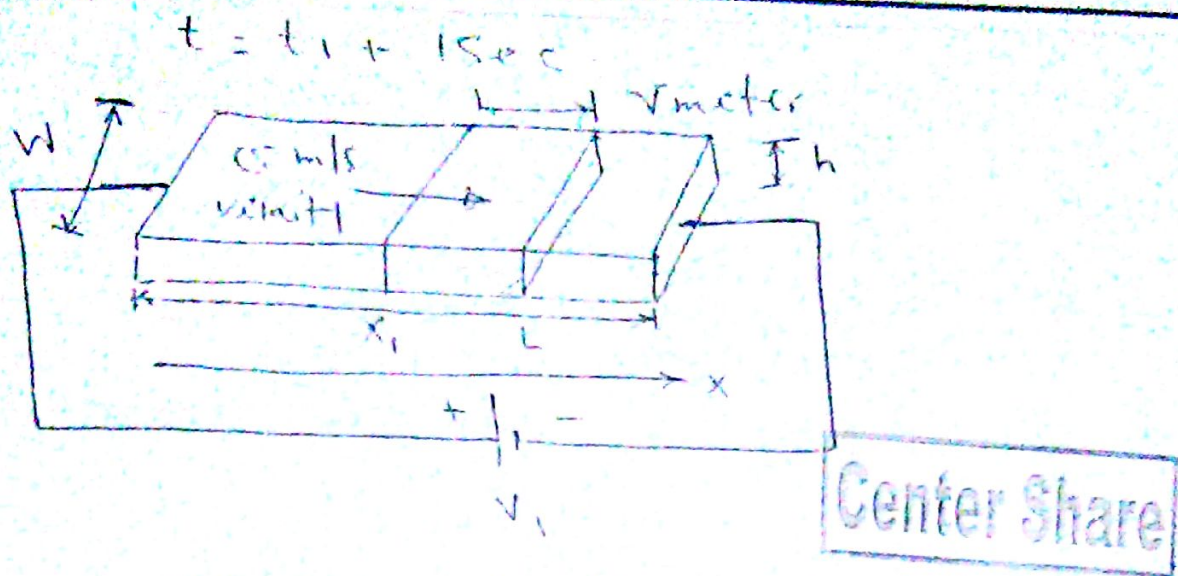
Channel length

⇒ Drain Current

What relation between the mobile charge density and the current?

assume a bar of semiconductor having uniform charge density (per unit length) equal to Q and carrying current I .





$\therefore I =$ Total Charge that Passes through the Cross section of the bar in one second

$$I = \frac{Q}{T} \quad \text{where } Q = \text{Total Charge} \quad T = \text{Time}$$

$$\therefore I = \frac{Q \times V}{T = 1 \text{ sec}} \quad \text{--- } \frac{1}{T}$$

$Q \rightarrow$ Total Charge

$$\therefore V = \frac{V}{T = 1 \text{ sec}}$$

$$\therefore I = Q \times V$$

Center Share $I = Q \times V \rightarrow *$

(Drift Current) \rightarrow MOSFET \rightarrow μ_n \rightarrow electron mobility

$$\therefore v_d = - \mu_n E \rightarrow \text{electric field}$$

\rightarrow electron mobility

$$\therefore I = + \mu_n \frac{dI(x)}{dx} \rightarrow (1)$$

$$\therefore Q(x) = W C_{ox} [V_{GS} - V(x) - V_{TH}] \quad \rightarrow (2)$$

(*) < (2) < (1) \rightarrow let me

$$\therefore I_D = W C_{ox} [V_{GS} - V(x) - V_{TH}] \mu_n \frac{dV(x)}{dx}$$

(V_{GS} & V_{DS}) terminal voltages \rightarrow I_D \rightarrow (5) \rightarrow (1) \rightarrow (2)

\rightarrow let me

$$I_D \times dx = W C_{ox} [V_{GS} - V(x) - V_{TH}] \mu_n dV(x)$$

$$\therefore \int_{x=0}^{x=L} I_D dx = \int_{V(x)=0}^{V(x)=V_{DS}} \mu_n C_{ox} W [V_{GS} - V(x) - V_{TH}] dV(x)$$

Center Share

$$\therefore I_D \times L = \mu_n C_{ox} W \left[V_{GS} V_{DS} - \frac{V_{DS}^2}{2} - V_{TH} V_{DS} \right]$$

$$\therefore I_D \times L = \mu_n C_{ox} W \left[(V_{GS} - V_{TH}) V_{DS} - \frac{V_{DS}^2}{2} \right]$$

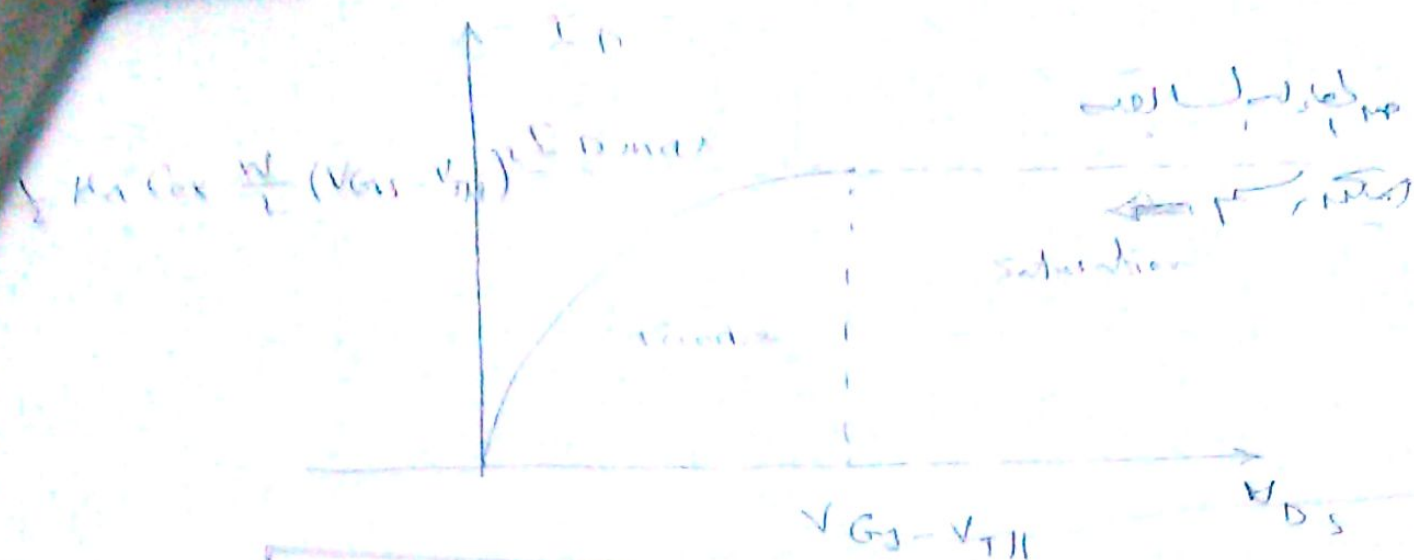
$$\therefore I_D = \frac{1}{2} \mu_n C_{ox} \frac{W}{L} \left[2(V_{GS} - V_{TH}) V_{DS} - V_{DS}^2 \right]$$

$$I_D \propto (\mu_n \propto C_{ox} \propto \frac{W}{L})$$

W/L Called (aspect ratio)

$$W/L = \frac{\mu_n}{\mu_p}$$

Current \rightarrow (5) \rightarrow (1) \rightarrow (2)



Center Share

(Pinch off) \rightarrow

at Pinch off $V_{DS} = V_{GS} - V_{TH}$

$\therefore I_{Dmax} = \frac{1}{2} \mu_n C_{ox} \frac{W}{L} (V_{GS} - V_{TH})^2$

EX-1.3

Plot $I_D - V_{DS}$ characteristics for different values of V_{GS} .

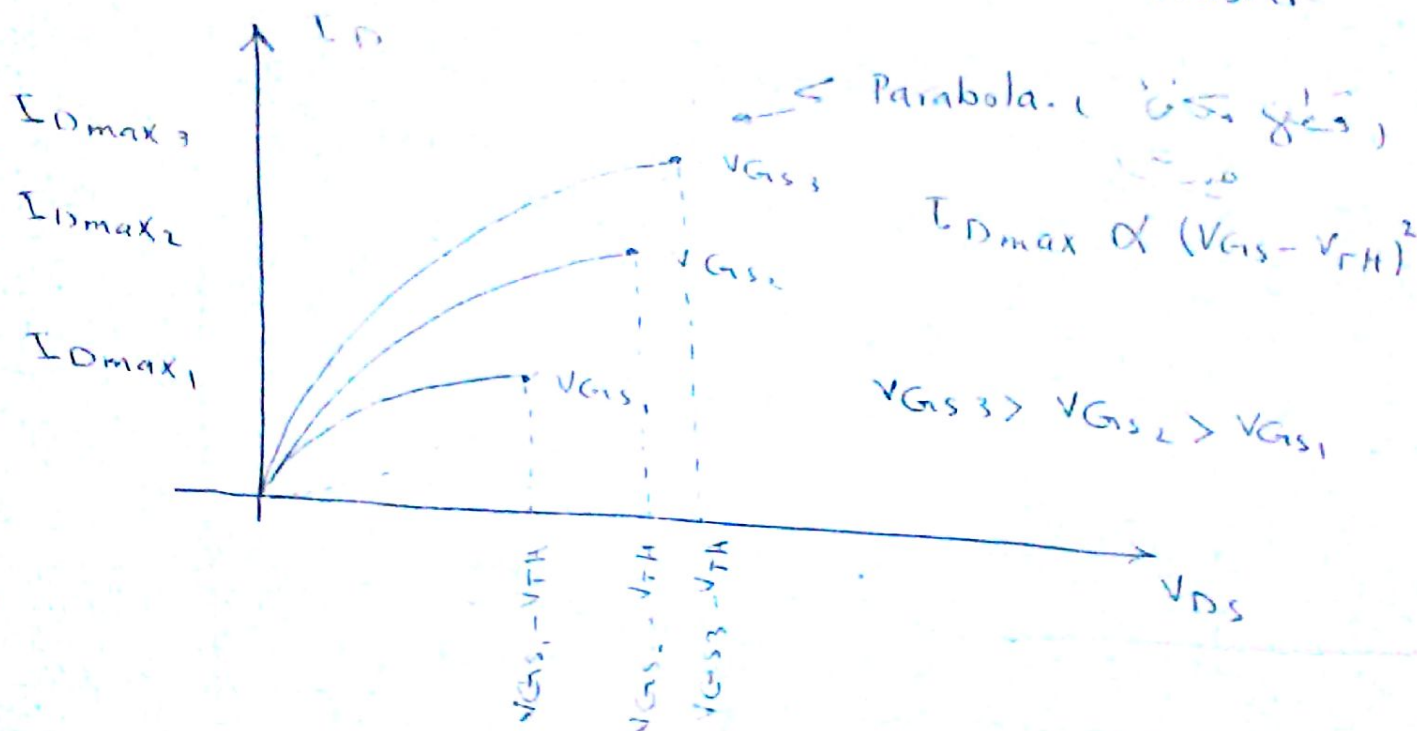
Solution

Center Share

$$\therefore I_D = \frac{1}{2} \mu_n C_{ox} \frac{W}{L} [2(V_{GS} - V_{TH}) V_{DS} - V_{DS}^2]$$

$$\therefore I_{Dmax} = \frac{1}{2} \mu_n C_{ox} \frac{W}{L} (V_{GS} - V_{TH})^2$$

$\therefore V_{GS}$ increased $\therefore I_{Dmax}$ increased



When $V_{DS} \rightarrow 0$, I_D is small

For MOSFET

if $V_{DS} \ll 2(V_{GS} - V_{TH})$

$\therefore (V_{DS})^2$ is very small

$$\therefore I_D = \frac{1}{2} \mu_n C_{ox} \frac{W}{L} \times 2 (V_{GS} - V_{TH}) V_{DS}$$

$$\therefore I_D = \mu_n C_{ox} \frac{W}{L} (V_{GS} - V_{TH}) V_{DS}$$

for $V_{DS} < I_D R_{on} \rightarrow$ MOSFET is in linear region

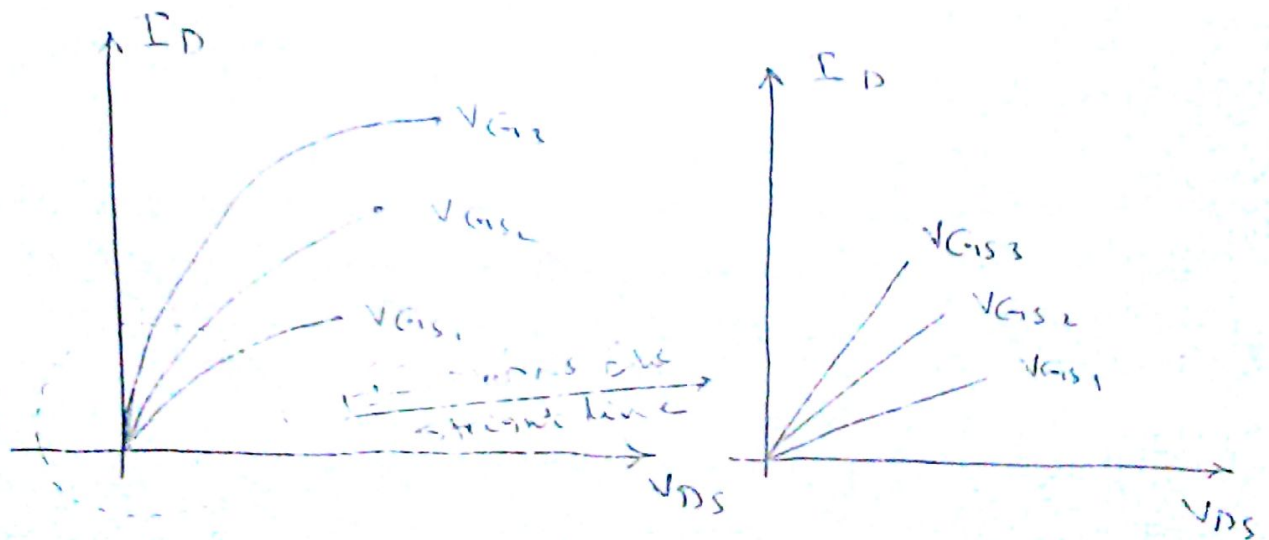
$$\therefore R_{on} (\text{on-resistor}) = \frac{V_{DS}}{I_D}$$

Center Share

$$\therefore R_{on} = \frac{1}{\mu_n C_{ox} \frac{W}{L} (V_{GS} - V_{TH})}$$

for $V_{DS} > I_D R_{on}$ MOSFET is in saturation

for $V_{DS} < I_D R_{on}$ MOSFET is in linear region



Note:

$$V_{GS} = V_{TH} \rightarrow \text{cutoff (} R_{on} \rightarrow \infty \text{)}$$

$$\therefore R_{on} = \infty$$

\therefore MOSFET operating as electronic switch

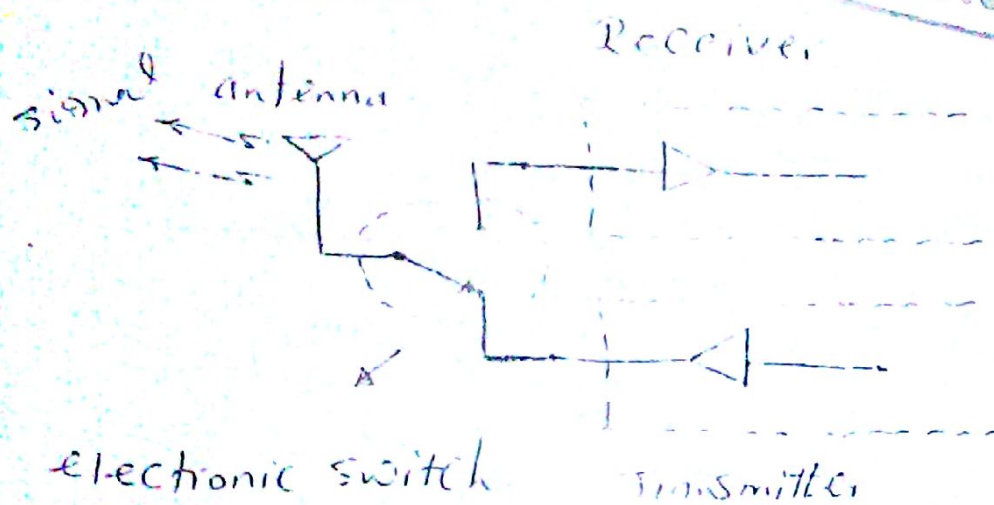
Switch MOSFET

EX. 1.4 →

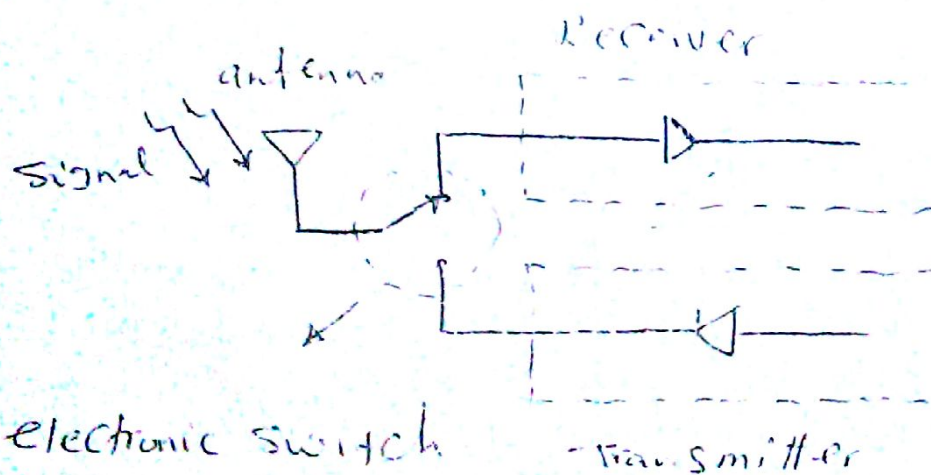
a Cordless Phone incorporates a single antenna for reception and Transmission - Explain how the system must be configured.

Solution

Center Share



هذا system
يستخدم
التيار الكهربائي
للتوصيل بين
التيار الكهربائي
والتيار الكهربائي
التيار الكهربائي



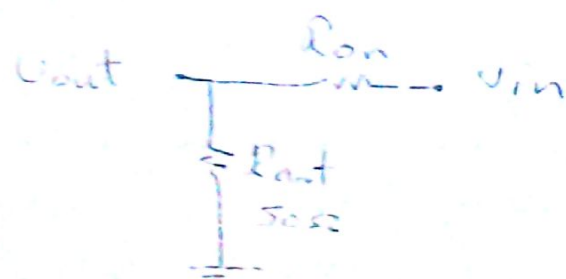
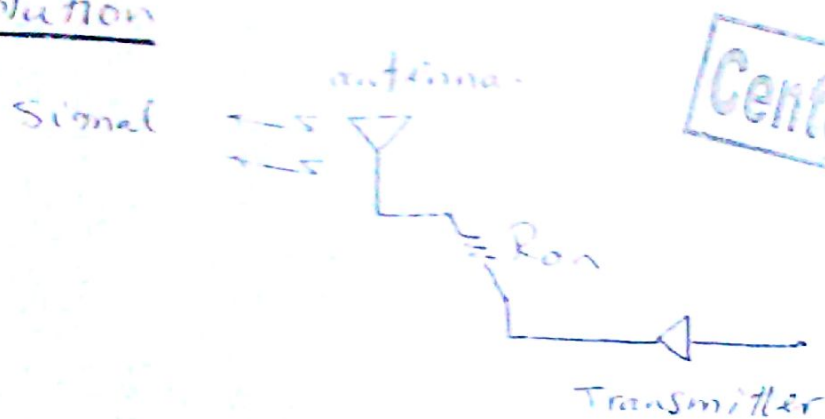
Switch MOSFET

low resistivity

$R_{on} \downarrow \leftarrow V_{GS} \uparrow \leftarrow W/L \uparrow$

EX. 1.5

in the Cordless Phone of example 1.4 the switch connecting the Transmitter to the antenna must attenuate the signal, e.g. by no more than 10%. if $V_{DD} = 1.8V$, $\mu_n C_{ox} = 100 \mu A/V^2$ and $V_{TH} = 0.4V$, determine the minimum required aspect ratio of the switch. assume the antenna can be modeled as a series resistor.

Solution

∴ attenuation $\leq 10\%$

∴ $\frac{V_{out}}{V_{in}} \geq 0.9$

∴ $V_{out} = V_{in} \times \frac{R_{ant}}{R_{ant} + R_{on}}$

$$\frac{Q_{out}}{Q_{in}} = \frac{P_{out}}{P_{out} + P_{on}}$$

$$\frac{P_{out}}{P_{out} + P_{on}} \geq 0.9$$

$$P_{out} \geq 0.9(P_{out} + P_{on})$$

$$0.1 P_{out} \geq 0.9 P_{on}$$

$$P_{on} \leq \frac{0.1 P_{out}}{0.9}$$

$$P_{out} = 50 \text{ mW}$$

$$P_{on} \leq 5.6 \text{ mW}$$

Center Share

$$P_{on} = \frac{1}{\mu_n C_{ox} \frac{W}{L} (V_{GS} - V_{TH})}$$

$$P_{on} \downarrow \Rightarrow V_{GS} \uparrow = V_{DD} = 1.8 \text{ V}$$

$$P_{on} = \frac{1}{100 \times 10^{-6} \times \frac{W}{L} (1.8 - 0.4)}$$

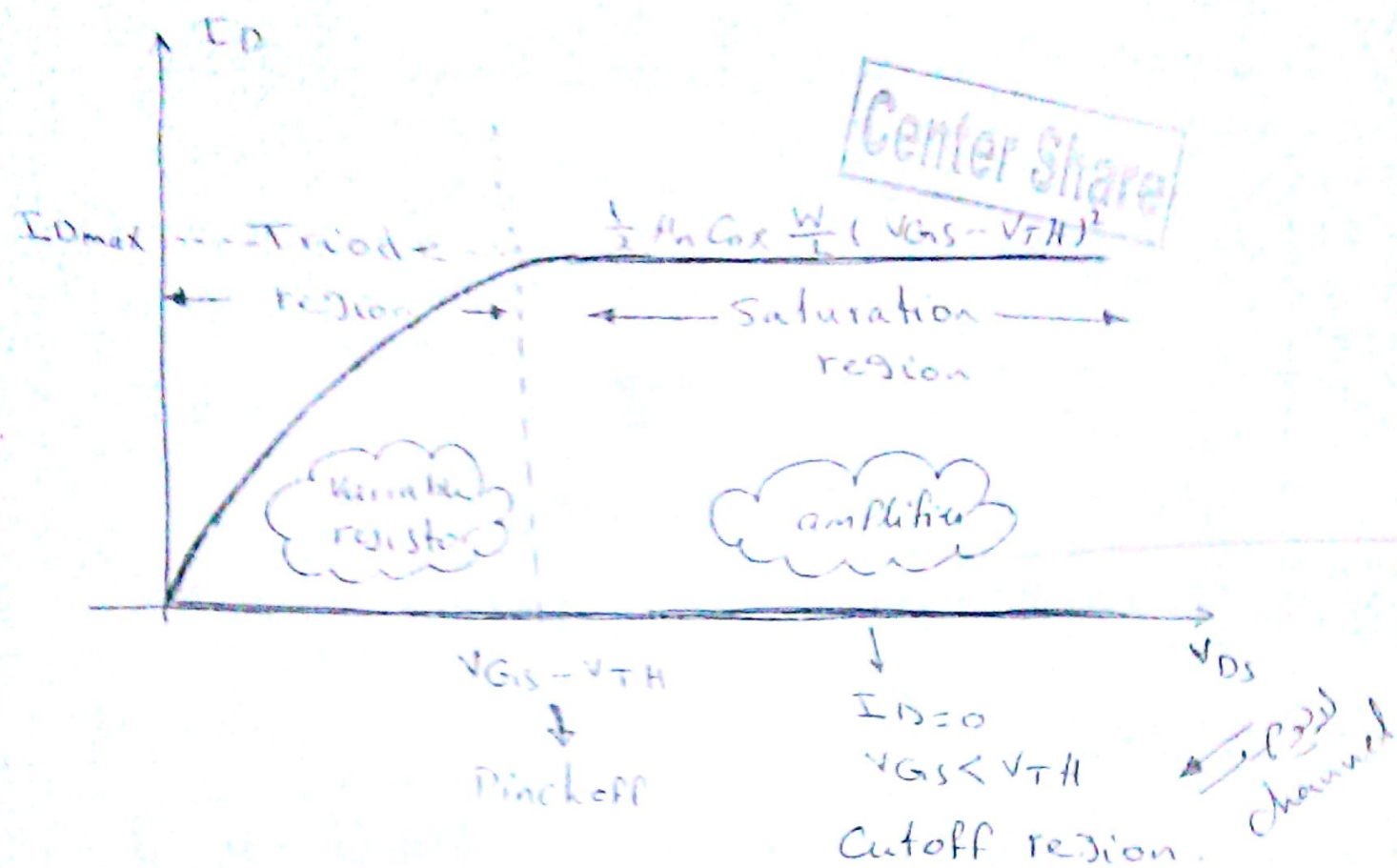
$$\frac{1}{100 \times 10^{-6} \times \frac{W}{L} (1.8 - 0.4)} \leq 5.6 \text{ mW}$$

$$1 \leq 7.24 \times 10^{-4} W/L$$

$$W/L \geq 1276 \quad \therefore W/L(\min) = 1276$$

Triode and Saturation regions

$$I_D = \frac{1}{2} \mu_n C_{ox} \frac{W}{L} [2(V_{GS} - V_{TH}) V_{DS} - V_{DS}^2]$$



*** MOSFET operates in Triode region or linear region when $V_{DS} < (V_{GS} - V_{TH})$

→ • if $V_{DS} \ll 2(V_{GS} - V_{TH})$ Called

MOSFET in deep Triode region and operate as resistor

$$R_{on} = \frac{1}{\mu_n C_{ox} \frac{W}{L} (V_{GS} - V_{TH})}$$

*** MOSFET operates in saturation region

When $V_{DS} > (V_{GS} - V_{TH})$ and MOSFET drain current becomes constant or reaches

saturation

$I_{D(sat)}$ (saturation) is the MOSFET drain current

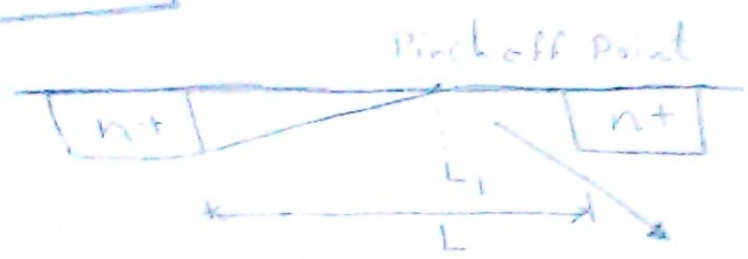
↓ S.I. with $V_{DS} > V_{GS} - V_{TH}$ Drain

• If $V_{DS} = V_{GS} - V_{TH}$ is MOSFET (Pinch off)

if V_{DS} increased the Pinch off Point shift toward the drain.

Center Share

(Drain) is $I_{D(sat)}$ (Pinch off Point)



$(V_{GS} - V_{TH})$ is V_{DS}

$I_{D(sat)}$ is the drain current when $V_{DS} = V_{GS} - V_{TH}$ and $V_{GS} = V_{TH}$

$$\int_{x=0}^{x=L_1} I_D dx = \int_{0 \leq x \leq L_1} \mu_n C_{ox} W [V_{GS} - V(x) - V_{TH}] dV(x)$$

$$\therefore I_D = \frac{1}{2} \mu_n C_{ox} \frac{W}{L_1} [V_{GS} - V_{TH}]^2$$

For $V_{DS} > V_{GS} - V_{TH}$ the MOSFET is in saturation region

∴ In saturation region I_D is independent of V_{DS}

$$V_{DS} \leq V_{GS} - V_{TH}$$

Center Share

∴ I_D (Drain saturation current) = I_{Dmax}

Note:

$(V_{GS} - V_{TH})$ called (overdrive voltage)

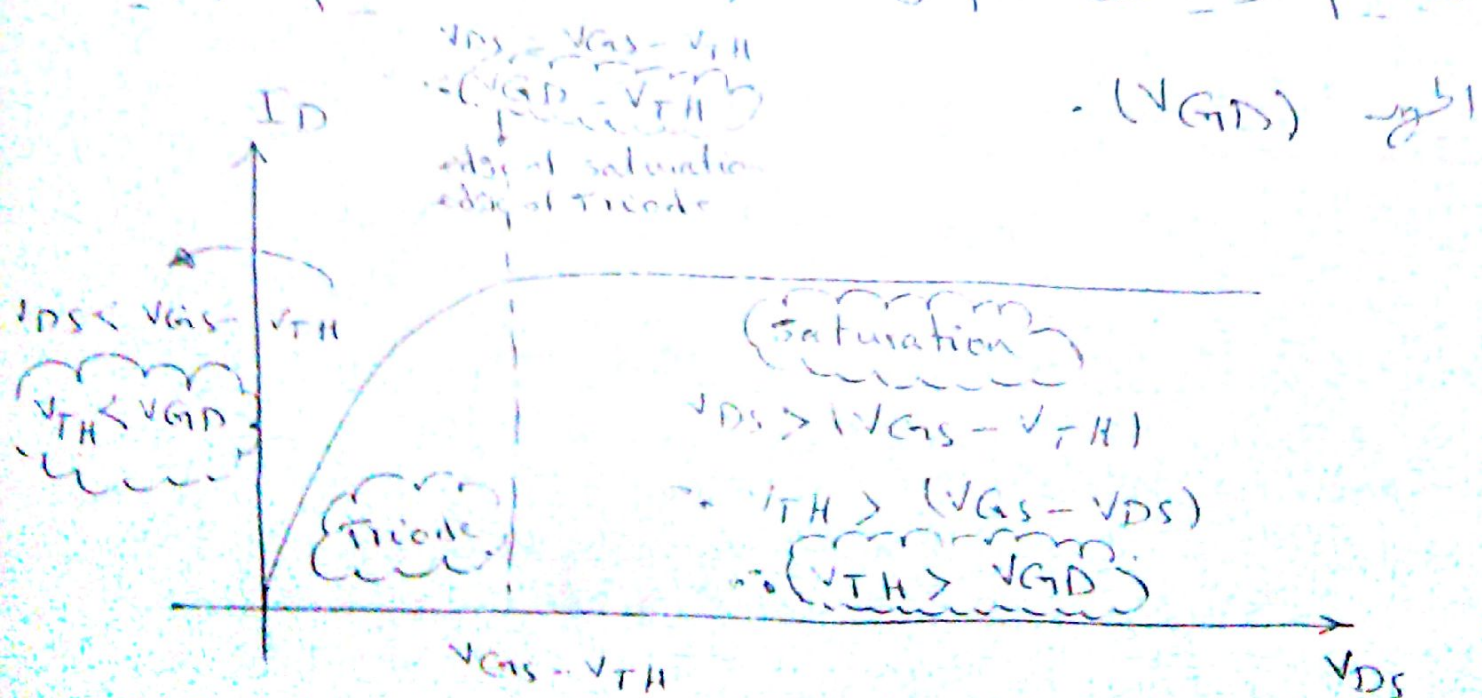
Note:

MOSFET sometimes called (square law) device

Where $I_D \propto (\text{overdrive voltage})^2$

⇒ determine the region of operation

For MOSFET I_D is given by



- MOSFET \Rightarrow Saturation region

$$V_{GD} < V_{TH} \quad , \quad V_{GS} > V_{TH}$$

- MOSFET \Rightarrow edge of saturation or edge of Triode

$$V_{GD} = V_{TH} \quad , \quad V_{GS} > V_{TH}$$

- MOSFET \Rightarrow Triode region

$$V_{GD} > V_{TH} \quad , \quad V_{GS} > V_{TH}$$

- MOSFET \Rightarrow Cutoff region

$$V_{GS} < V_{TH} \quad \text{No channel}$$

- MOSFET \Rightarrow deep Triode region

$$V_{DS} \leq 2(V_{GS} - V_{TH}) \quad , \quad V_{GS} > V_{TH}$$

* MOSFET in Saturation region operating

a) Current source with current I_{Dmax} .

(Saturation)

\Rightarrow Using current source MOSFET as

$$I_{Dmax} \Rightarrow \bar{I}_{Dmax}$$

$$I_{Dmax} = \frac{1}{2} \mu_n C_{ox} \frac{W}{L} (V_{GS} - V_{TH})^2$$

$$\text{as } V_{GS} \uparrow \quad \text{as } I_D \uparrow$$

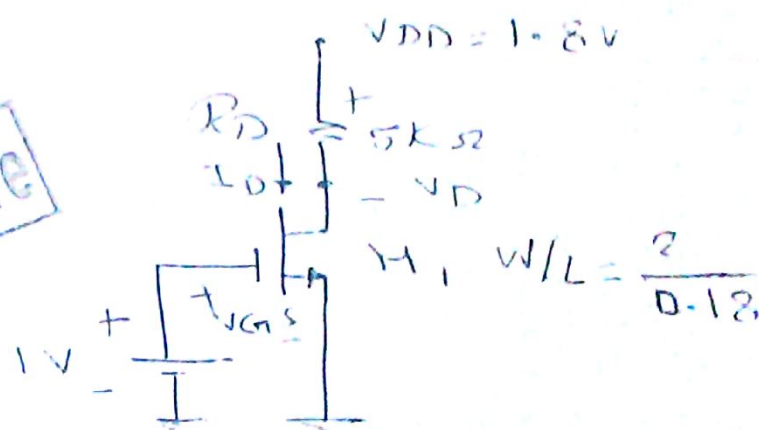
is MOSFET called voltage controlled current source.

Ex. 1-6

Calculate the bias current of M_1 in fig.

Assume the $\mu_n C_{ox} = 100 \mu A/V^2$ and $V_{TH} = 0.4V$ if the gate voltage increases by $10mV$. What is the change in the drain voltage?

Center Share



Solution

Assume M_1 is in saturation region.

Assume M_1 in saturation region.

$$V_{GS} = 1V$$

$$\therefore I_D = \frac{1}{2} \mu_n C_{ox} \frac{W}{L} (V_{GS} - V_{TH})^2$$

$$\therefore I_D = \frac{1}{2} \times 100 \times 10^{-6} \times \frac{2}{0.18} (1 - 0.4)^2 = 200 \mu A$$

لا بد من إكمال التمرين

$$V_D = V_{DD} - I_D \times R_D$$

$$\therefore V_D = 1.8 - 200 \mu A \times 5k\Omega = 0.8V$$

$$\therefore V_{GD} = 1 - 0.8 = 0.2 < V_{TH}$$

\therefore MOSFET in saturation region.

$$\bullet \text{ i.p. } V_G = 1 + 10mV = 1.01V$$

assume M_1 in saturation region.

$$\therefore I_D = \frac{1}{2} \mu_n C_{ox} \frac{W}{L} (V_{GS} - V_{TH})^2$$

$$\therefore I_D = \frac{1}{2} \times 100 \times 10^{-6} \times \frac{2}{0.18} (1.01 - 0.4)^2$$

$$\therefore I_D = 206.7 \mu A$$

$$\therefore V_D = V_{DD} - I_D \times R_D$$

$$\therefore V_D = 1.8 - 206.7 \mu A \times 5k\Omega = 0.766V$$

$$\therefore V_{GD} = (1 - 0.766) < V_{TH}$$

$\therefore M_1$ in saturation region.

change in V_D

$$= 0.8 - 0.766 = 34mV$$

For Share

Ge

BJT & MOSFET Comparison

BJT	MOSFET
edge of active or saturation $V_{BE} = 0$ or $V_{BE} = V_{CE}$	edge of saturation or Triode region $V_{GD} = V_{TH}$ or $V_{DS} = V_{GS} - V_{TH}$
$I_C - V_{BE}$ the relation is exponential	$I_D - V_{GS}$ the relation square law
in all BJT circuit have same dimensions	aspects ratio of each MOSFET may be chosen to satisfy the requirements
the R_{in} very low for R_{in} of MOSFET	the gate of MOSFET Draw no bias current so that R_{in} is very high

MOSFET

$V_{GS} - V_{TH}$ I_D Power \downarrow

$V_{GS} - V_{TH}$

I_D